

MT18SD-H

- MicroThin为附18 μm 载体铜箔的超薄铜箔。
MicroThin is ultra thin foil with 18 μm carrier foil.
- 最适用于线宽/线距(L/S) = 35/35~40/40之应用。
Usable for fine pitch pattern L/S = 35/35 - 40/40 formation.

用途/Application

- IC封装基板
/Semiconductor Package
- 高密度互连技术板
/High Density Interconnect

构成/Composition



生产地点/Production Site

- 日本 / Japan
- 马来西亚/Malaysia

代表性特性数据/Representative data

	μm	Area weight (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)@FR-4
MT18SD-H	3	39	3	-	-	1.4
	5	57	3	-	-	1.4

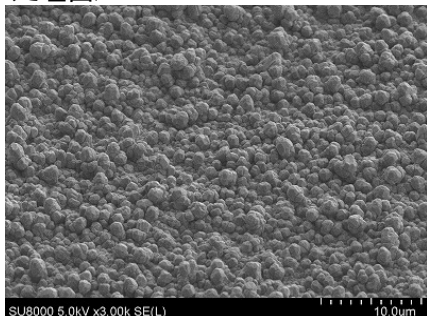
※上述表列为代表性数据非保证值

This is representative data, not guaranteed.

※Peel Strength为增镀到35 μm 厚度之后的测试值

Evaluated after plated up to 35 μm .

处理面/Laminate side



阻剂面/ resist side

